MA2SV05

Silicon epitaxial planar type

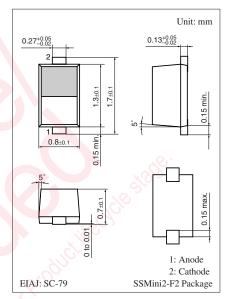
For VCO

■ Features

- ullet Good linearity and large capacitance-ratio in $C_D V_R$ relation
- Small series resistance r_D
- SS-Mini type package, allowing downsizing of equipment and automatic insertion through the taping package

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Reverse voltage	V _R	6	V
Junction temperature	T _j	150	°C
Storage temperature	T _{stg}	-55 to +150	°C



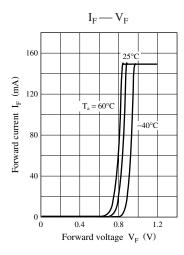
Marking Symbol: 3A

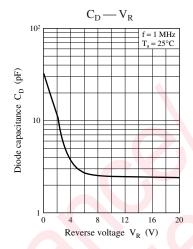
■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

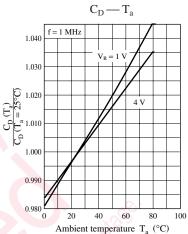
Parameter		Symbol	Conditions	Min	Тур	Max	Unit
Reverse current		I_R	$V_R = 5 \text{ V}$	100	0,	10	nA
Diode capacitance		C _{D(1V)}	$V_R = 1 \text{ V, f} = 1 \text{ MHz}$	18.5)	20.5	pF
		$C_{D(4V)}$	$V_R = 4 \text{ V}, f = 1 \text{ MHz}$	3.6		4.1	
Capacitance ratio		C _{D(1V)} /C _{D(4V)}	5): 6): 6	4.7			_
Series resistance *	10°	r_{D}	$V_R = 4 \text{ V, f} = 470 \text{ MHz}$			0.65	Ω

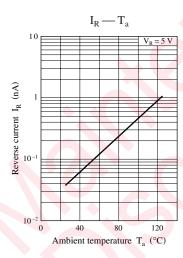
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

- 2. Absolute frequency of input and output is 470 MHz.
- 3. *: Measuring instrument; YHP MODEL 4191A RF IMPEDANCE ANALYZER









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